TFT DISPLAY SPECIFICATION

曜凌光電股份有限公司
Raystar Optronics, Inc.
42881台中市大雅區科雅路25號5樓
5F, No. 25, Keya Road, Daya Dist., Taichung City 42881, Taiwan
T：+886-4-2565-0761 | F：+886-4-2565-0760
sales@raystar-optronics.com | www.raystar-optronics.com

RFC350X-AWW-DNG

SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:

TFT Display Inspection Specification: https://www.raystar-optronics.com/download/products.htm
Precaution in use of TFT module: https://www.raystar-optronics.com/download/declaration.htm

Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0 A B	2022/01/19 2022/02/24 2023/07/13		First issue Modify VDDT Remove Inspection Specification

Contents

1.Module Classification Information

R	F	C	35	0X	-	A	W	W	-	D	N	G
1	2	3	4	5	-	6	7	8	-	9	10	11

Item	Description		
1	R：Raystar Optronics Inc.		
2	Display Type：F→TFT Type, J→ Custom TFT		
3	Solution: A: 128x160 B:320x234 C:320x240 D:480x234 E:480x272 F:800x480 G:640x480 H:1024x600 I:320x480 J:240x320 K:1280x800 L:240x400 M:1024x768 N:128x128 O:480x800 P:640x320 Q:800x600 S:480x128 T:800x320		
4	Display Size：3.5” TFT		
5	Version Code.		
6	Model Type: A：TFT LCD E：TFT+FR+CONTROL BOARD J：TFT+FR+A/D BOARD N：TFT+FR+A/D BOARD+CONTROL BOARD S：TFT+FR+POWER BOARD (DC TO DC) 1：TFT+CONTROL BOARD	6：TFT+FR H：TFT+D/V BOARD I：TFT+FR+D/V BOARD B：TFT+POWER BD	
7	Polarizer Type, Temperature range, View direction	I→Transmissive, W. T, 6:00 ; C→Transmissive, N. T, 6:00 L→Transmissive, W.T,12:00 ; F→Transmissive, N.T,12:00 Y→Transmissive,W.T, IPS TFT ; W→Transmissive, Super W.T, IPS TFT A→Transmissive, N.T, IPS TFT Z→Transmissive, W.T, O-TFT R→Transmissive, Super W.T, O-TFT N→Transmissive, Super W.T, 6:00; Q→Transmissive, Super W.T, 12:00 V→Transmissive, Super W.T, VA TFT	
8	Backlight	W：LED, White	H：LED, High Light White
		F：CCFL, White	
9	Driver Method	D: Digital A: Analog L：LVDS M:MIPI	
10	Interface	N：without control board A：8Bit B：16Bit S:SPI Interface R: RS232 U:USB I: I2C	
11	TS	N：Without TS S：resistive touch panel C：capacitive touch panel capacitive touch panel (G-F-F) G：capacitive touch panel(G-G)	

2.Summary

TFT 3.5”is a IPS transmissive type color active matrix TFT liquid crystal display that use amorphous silicon TFT as switching devices. This module is a composed of a TFT_LCD module, It is usually designed for industrial application and this module follows RoHs.

3.General Specifications

- Size: 3.5 inch
- Dot Matrix: 320 x RGBx240(TFT) dots
- Module dimension: 76.84(W) x 63.84(H) x 4.86(D) mm
- Active area: 70.08 x 52.56 mm
- Pixel pitch: 0.219 x 0.219 mm
- LCD type: TFT, normally black, Transmissive
- View Direction: 80/80/80/80
- Driver IC: ST7272A or equivalent
- Interface ：24-bit RGB
- Aspect Ratio: 4:3
- Backlight Type: LED,Normally White
- CTP IC: ILI2130 or equivalent
- CTP Interface: I2C
- CTP FW Version: 0x07.0x00.0x00.0x00.0x00.0x35.0x5A.0x01
- CTP Resolution:16384*16384
- With /Without TP: With CTP
- Surface: Glare

*Color tone slight changed by temperature and driving voltage.

4.Interface

4.1. LCM PIN Definition

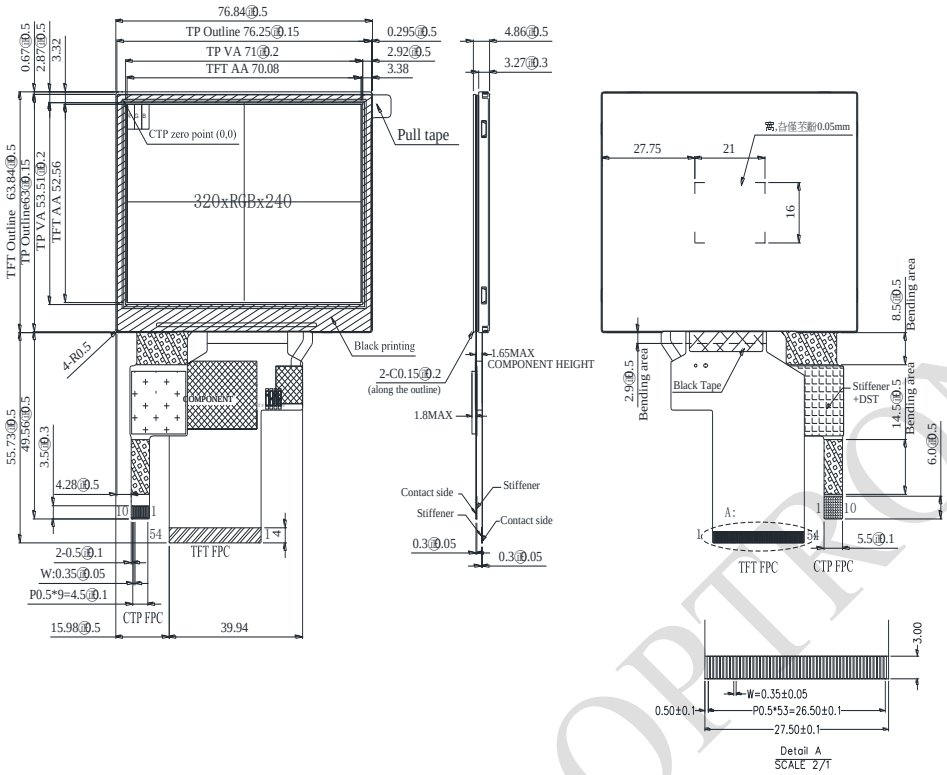
Pin	Symbol	Function	Remark
1	LED-	Power for LED backlight cathode	
2	LED-	Power for LED backlight cathode	
3	LED+	Power for LED backlight anode	
4	LED+	Power for LED backlight anode	
5	NC	No connect	
6	NC	No connect	
7	NC(SPI_IIC_SEL)	No connect	
8	/RESET	Hardware reset	
9	NC(CS)	No connect	
10	NC(SDA)	No connect	
11	NC(SCL)	No connect	
12	B0	Data bus	
13	B1	Data bus	
14	B2	Data bus	
15	B3	Data bus	
16	B4	Data bus	
17	B5	Data bus	
18	B6	Data bus	
19	B7	Data bus	
20	G0	Data bus	
21	G1	Data bus	
22	G2	Data bus	
23	G3	Data bus	
24	G4	Data bus	
25	G5	Data bus	
26	G6	Data bus	
27	G7	Data bus	
28	R0	Data bus	
29	R1	Data bus	

30	R2	Data bus	
31	R3	Data bus	
32	R4	Data bus	
33	R5	Data bus	
34	R6	Data bus	
35	R7	Data bus	
36	HSYNC	Horizontal sync signal, default is negative polarity.	
37	VSYNC	Vertical sync signal, default is negative polarity.	
38	DCLK	Dot-clock signal and oscillator source	
39	NC(HDIR)	No connect	
40	NC(VDIR)	No connect	
41	VCC	Power Supply	
42	VCC	Power Supply	
43	NC	No connect	
44	NC	No connect	
45	NC(PARA_SERI)	No connect	
46	NC(BIST_EN)	No connect	
47	NC(ENPROG)	No connect	
48	NC	No connect	
49	NC	No connect	
50	NC	No connect	
51	NC(DISP)	No connect	
52	DE	Data input enable. Display access is enabled when DE is “H” .	
53	GND	Ground	
54	GND	Ground	

4.2. CTP PIN Definition

Pin	Symbol	Function	Remark
1	VSS	System ground pin of the IC. Connect to system ground.	
2	VDDT	Power Supply : +3.3V	
3	SCL	I2C clock input	
4	NC	No connect	
5	SDA	I2C data input and output	
6	NC	No connect	
7	/RST	External Reset, Low is active	
8	NC	No connect	
9	/INT	External interrupt to the host	
10	VSS	System ground pin of the IC. Connect to system ground.	

5.Contour Drawing



TFT

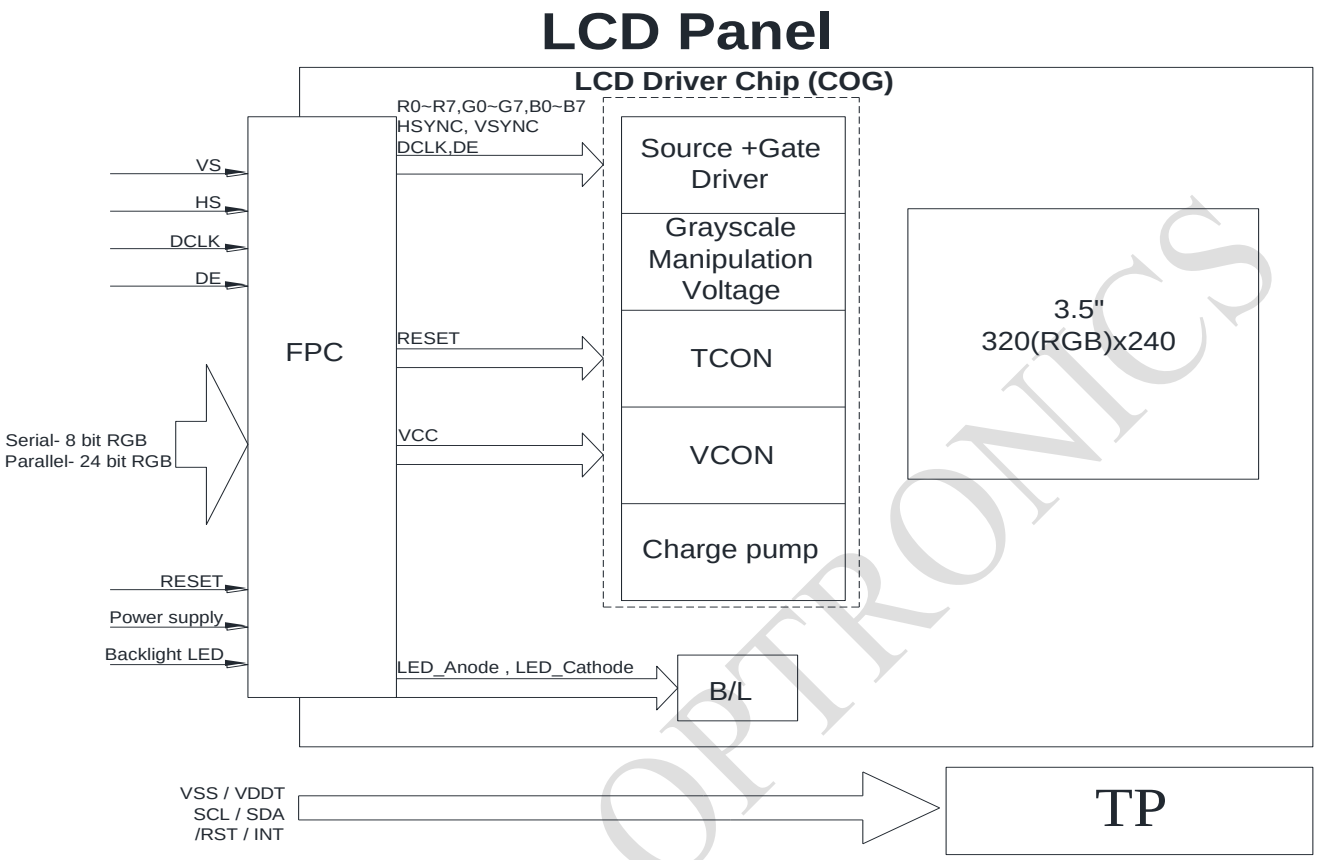
PinNo.	Symbol	PinNo.	Symbol
1	LED-	28	R0
2	LED-	29	R1
3	LED+	30	R2
4	LED+	31	R3
5	NC	32	R4
6	NC	33	R5
7	NC(SPI_IIC_SEL)	34	R6
8	/RESET	35	R7
9	NC(CS)	36	HSYNC
10	NC(SDA)	37	VSYNC
11	NC(SCL)	38	DCLK
12	B0	39	NC(HDIR)
13	B1	40	NC(VDIR)
14	B2	41	VCC
15	B3	42	VCC
16	B4	43	NC
17	B5	44	NC
18	B6	45	NC(PARA_SERI)
19	B7	46	NC(BIST_EN)
20	G0	47	NC(ENPROG)
21	G1	48	NC
22	G2	49	NC
23	G3	50	NC
24	G4	51	NC(DISP)
25	G5	52	DE
26	G6	53	GND
27	G7	54	GND

CTP

PIN NO.	SYMBOL	PIN NO.	SYMBOL
1	VSS	6	NC
2	VDDT	7	/RST
3	SCL	8	NC
4	NC	9	/INT
5	SDA	10	VSS

The non-specified tolerance of dimension is ±0.3 mm .

6.Block Diagram



7.Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	TOP	-30	—	+85	□
Storage Temperature	TST	-30	—	+85	□

Note: Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above

1. Temp. □60□, 90% RH MAX. Temp.＞60□, Absolute humidity shall be less than 90% RH at 60□

8.Electrical Characteristics

8.1. Operating conditions:

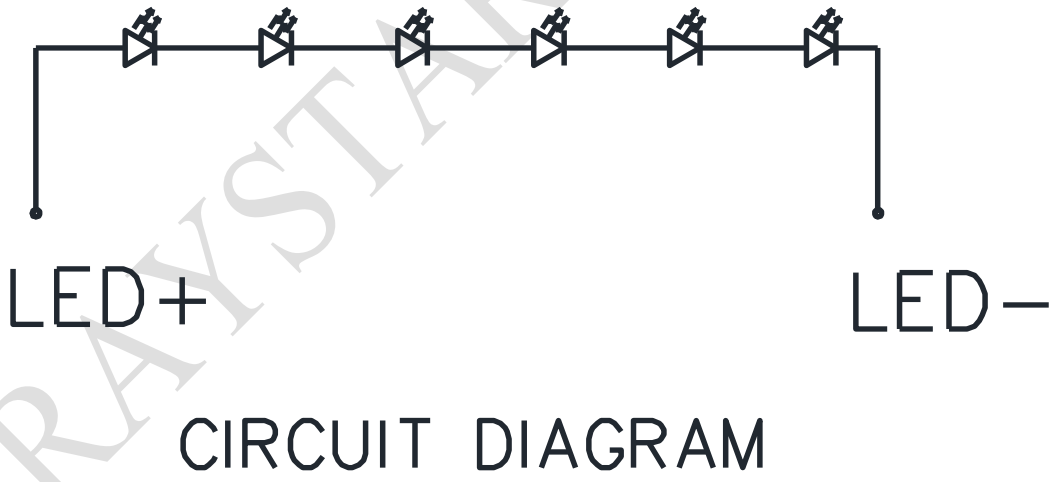
Item	Symbol	Min	Typ	Max	Unit	Remark
Supply Voltage For LCM	VCC	3.0	3.3	3.6	V	
Supply Current For LCM	ICC	—	20	30	mA	Note 1
Supply CTP	VDDT	3.1	3.3	3.5	V	VDDT
	I_{CTP}	—	45	68	mA	I_{CTP}

Note 1 : This value is test for VCC =3.3V , Ta=25 ℃ only

8.2. LED driving conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Remark
LED current	-	-	20	-	mA	-
Power Consumption	-	324	384	408	mW	-
LED voltage	LED+	16.2	19.2	20.4	V	Note 1
LED Life Time	-	-	50,000	-	Hr	Note 2,3,4

Note 1 : There are 1 Groups LED



CIRCUIT DIAGRAM

Note 2 : Ta = 25 ℃
Note 3 : Brightness to be decreased to 50% of the initial value
Note 4 : The single LED lamp case

9.AC Characteristics

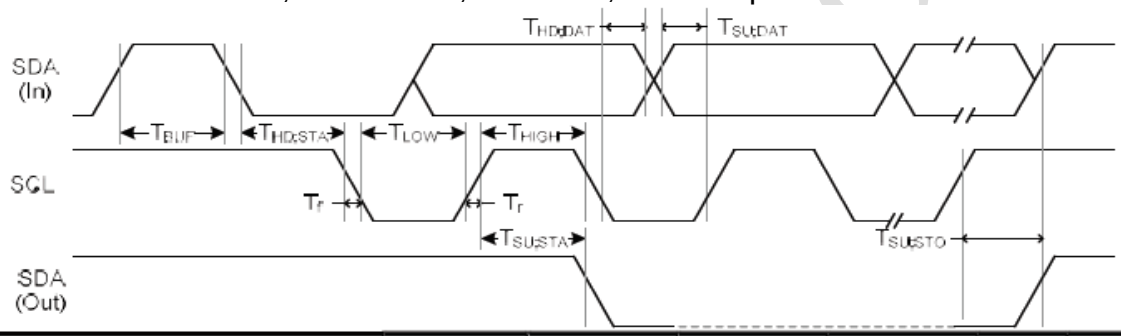
9.1. System Operation AC Characteristics

PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25^{0}C, Bare Chip

Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
VDD Power Source Slew Time	TPOR	-	-	20	ms	From 0V to 99% VDD
GRB Pulse Width	tRSTW	10	50	-	us	R=10Kohm, C=1uF
SD Output Stable Time	Tst	-	-	12	us	Output settled within +20mV Loading = 6.8k+28.2pF.
GD Output Rise and Fall Time	Tgst	-	-	6	us	Output settled (5%~95%), Loading = 4.7k+29.8pF

9.2. System Bus Timing for I2C Interface

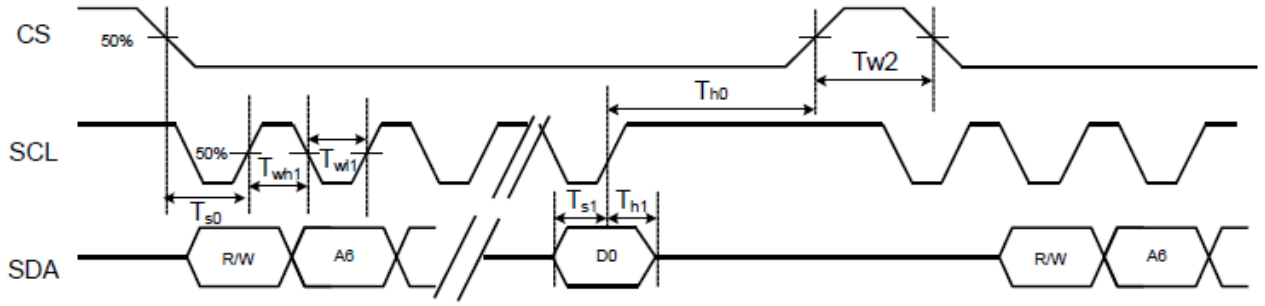
PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25^{0}C, Bare Chip



Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
SCL Clock Frequency	FSCL	-	-	400	KHz	
SCL Clock Low Period	TLOW	1300	-	-	ns	
SCL Clock High Period	THIGH	600	-	-	ns	
Signal Rise Time	Tr	20+0.1Cb	-	300	ns	
Signal Fall Time	Tf	20+0.1Cb	-	300	ns	
Start Condition Setup Time	TSU;STA	600	-	-	ns	
Start Condition Hold Time	THD;STA	600	-	-	ns	
Data Setup Time	TSU;DAT	100	-	-	ns	
Data Hold Time	THD;DAT	0	-	900	ns	
Setup Time for STOP Condition	TSU;STO	600	-	-	ns	
Bus Free Time Between a STOP and START	TBUF	100	-	-	ns	
Capacitive load represented by each bus line		Cb		400	pF	

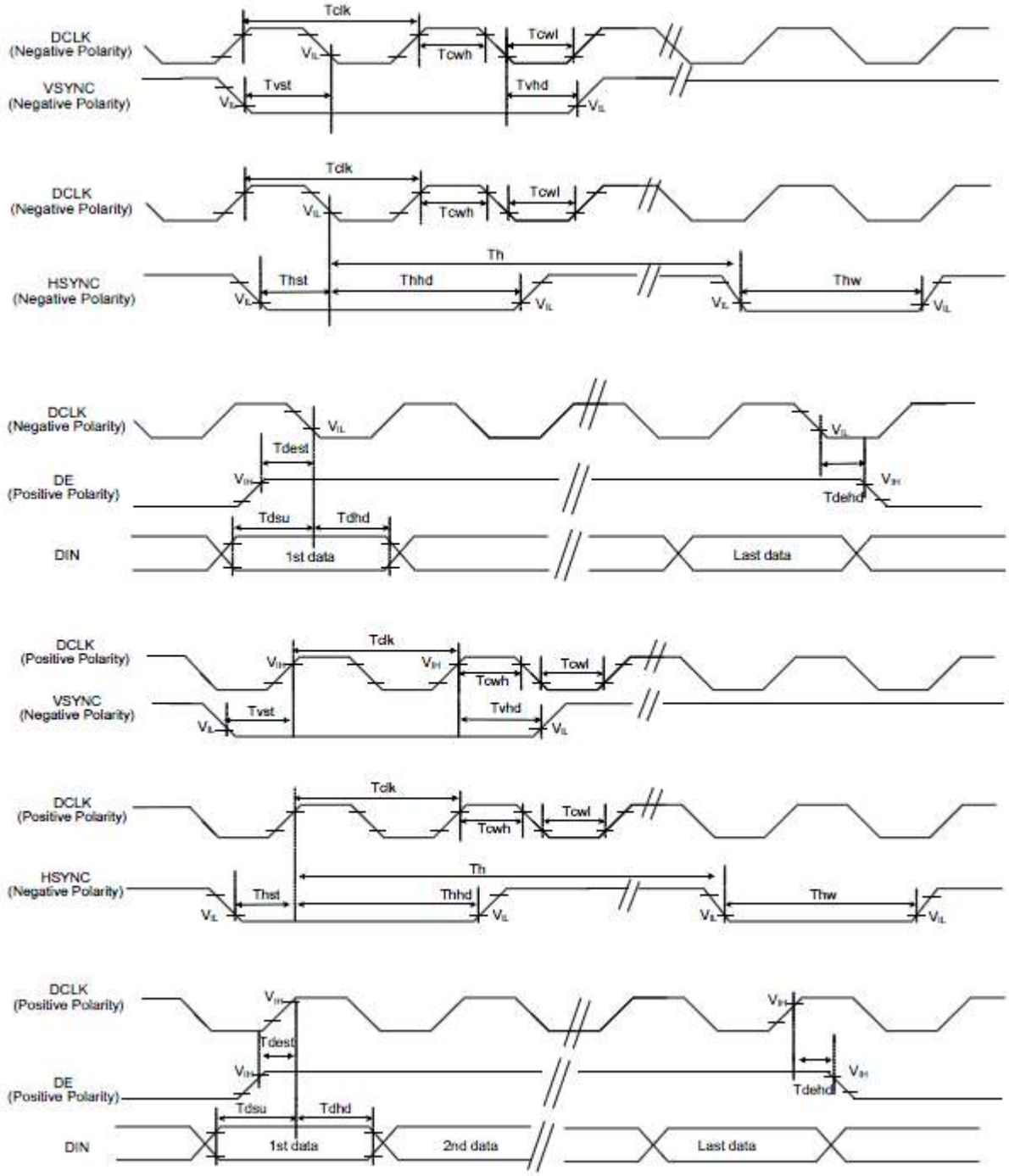
9.3. System Bus Timing for 3-Wire SPI Interface

PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25^{0}C, Bare Chip



Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
CS Input Setup Time	Ts0	50	-	-	ns	
Serial Data Input Setup Time	Ts1	50	-	-	ns	
CS Input Hold Time	Th0	50	-	-	ns	
Serial Data Input Hold Time	Th1	50	-	-	ns	
SCL Write Pulse High Width	Twh1	50	-	2000	ns	
SCL Write Pulse Low Width	Twl1	50	-	2000	ns	
SCL Read Pulse High Width	Trh1	300		2000	ns	
SCL Read Pulse Low Width	Trl1	300		2000	ns	
CS Pulse High Width	Tw2	400	-	-	ns	

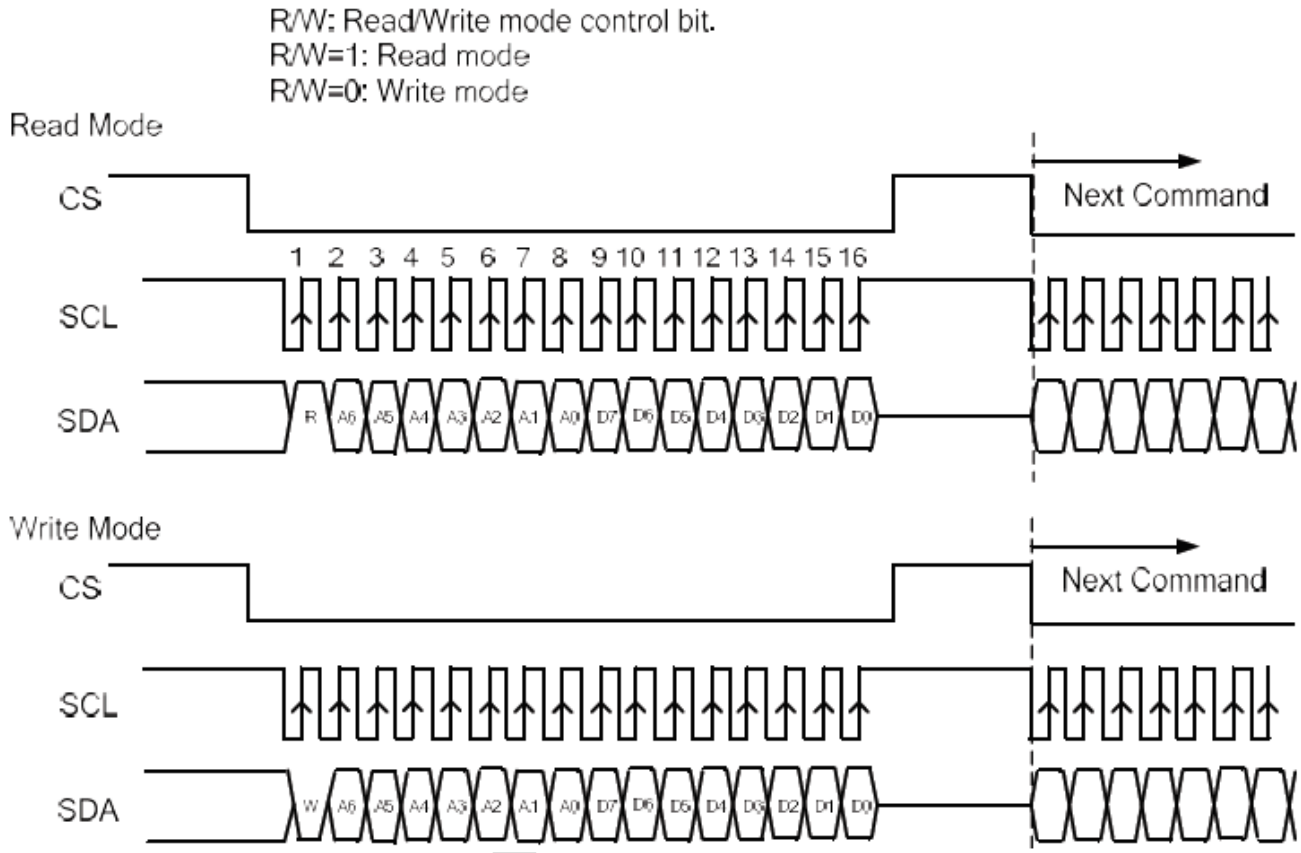
9.4. System Bus Timing for RGB Interface



Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
CLK Pulse Duty	Tclk	40	50	60	%	
HSYNC Width	Thw	2	-	-	DCLK	
VSYNC Setup Time	Tvst	12	-	-	ns	
VSYNC Hold Time	Tvhd	12	-	-	ns	
HSYNC Setup Time	Thst	12	-	-	ns	
HSYNC Hold Time	Thhd	12	-	-	ns	
Data Setup Time	Tdsu	12	-	-	ns	
Data Hold Time	Tdhd	12	-	-	ns	
DE Setup Time	Tdest	12	-	-	ns	
DE Hold Time	Tdehd	12	-	-	ns	

10.Communication Interface

10.1. 3-wire Serial Interface



a. Each serial command consists of 16 bits of data which is loaded one bit a time at the rising edge of serial clock SCL.

b. Command loading operation starts from the falling edge of CS and is completed at the next rising edge of CS.

c. The serial control block is operational after power on reset, but commands are established by the VSYNC signal. If command is transferred multiple times for the same register, the last command before the VSYNC signal is valid.

d. If less than 16 bits of SCL are input while CS is low, the transferred data is ignored.

e. If 16 bits or more of SCL are input while CS is low, the previous 16 bits of transferred data before then rising edge of CS pulse are valid data.

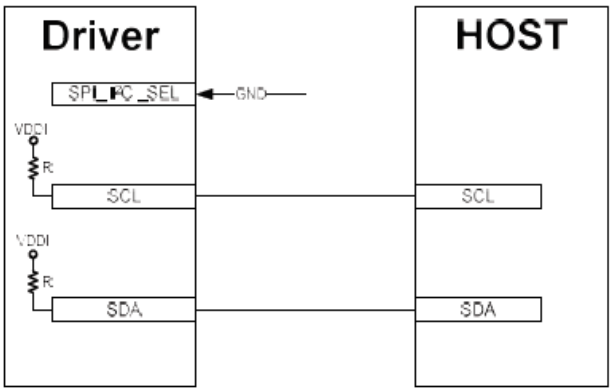
f. Serial block operates with the SCL clock

g. Serial data can be accepted in the power save mode.

h. After power on reset or GRB reset, it is required 100ms delay to begin SPI communication.

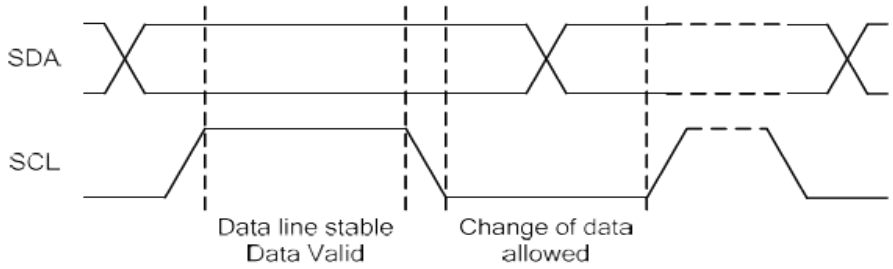
10.2. I2C Interface

The I2C Interface is bi-directional two-line communication between different ICs or modules. The two lines are a Serial Data line (SDA) and a Serial Clock line (SCL). Both lines have built-in pull up resistor which drives SDA and SCL to high when the bus is not busy. Data transfer can be initiated only when the bus is not busy.



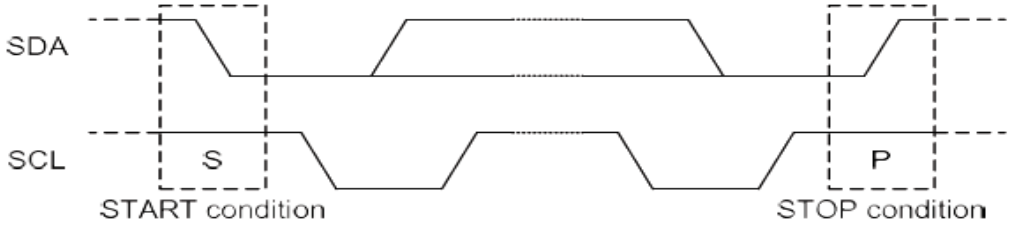
1. Bit Transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse because changes of SDA line at this time will be interpreted as START or STOP. Bit transfer is illustrated as follows.

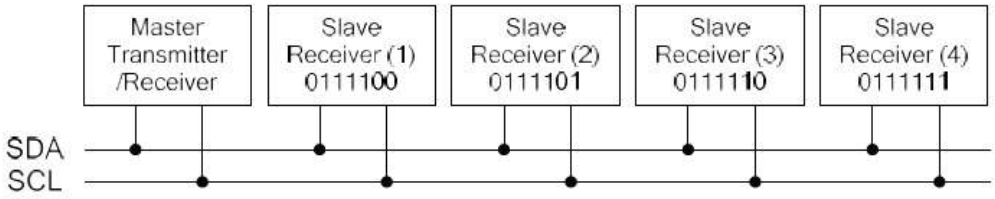


2. START and STOP Conditions

Both SDA and SCL lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of SDA, while SCL is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of SDA while SCL is HIGH is defined as the STOP condition (P). The START and STOP conditions are illustrated as follows.



3. System Configuration



The system configuration is illustrated above and some word-definitions are explained below:

a. Transmitter: the device which sends the data to the bus.

b. Receiver: the device which receives the data from the bus.

c. Master: the device which initiates a transfer generates clock signals and terminates a transfer.

d. Slave: the device which is addressed by a master.

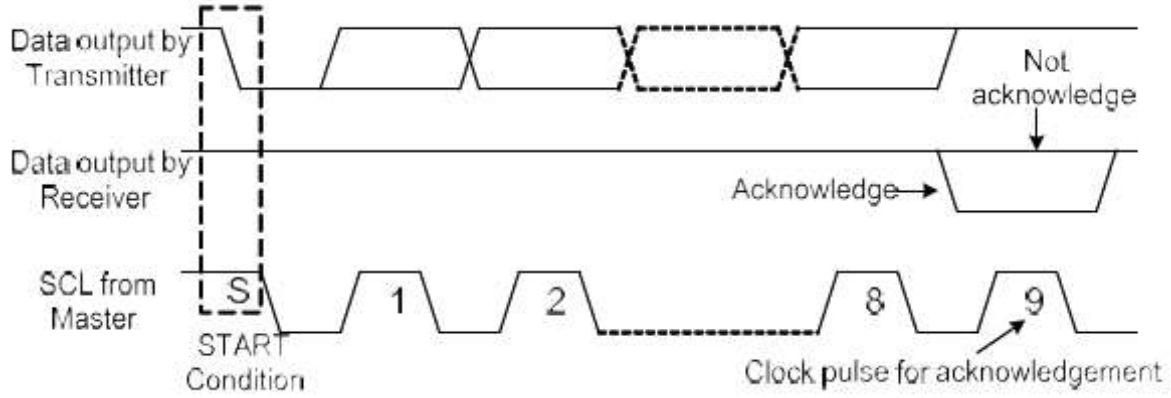
e. Multi-Master: more than one master can attempt to control the bus at the same time without corrupting the message.

f. Arbitration: the procedure to ensure that, if more than one master tries to control the bus simultaneously, only one is allowed to do so and the message is not corrupted.

g. Synchronization: procedure to synchronize the clock signals of two or more devices.

4.Acknowledgment

Each byte of eight bits is followed by an acknowledge-bit. The acknowledge-bit is a HIGH signal put on SDA by the transmitter during the time when the master generates an extra acknowledge-related clock pulse. A slave receiver which is addressed must generate an acknowledge-bit after the reception of each byte. A master receiver must also generate an acknowledge-bit after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges must pull-down the SDA line during the acknowledge-clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledgerelated clock pulse (set-up and hold times must be taken into consideration). A master receiver must signal an end-of-data to the slave transmitter by not generating an acknowledge-bit on the last byte that has been clocked out of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a STOP condition. Acknowledgement on the I2C Interface is illustrated as follows.

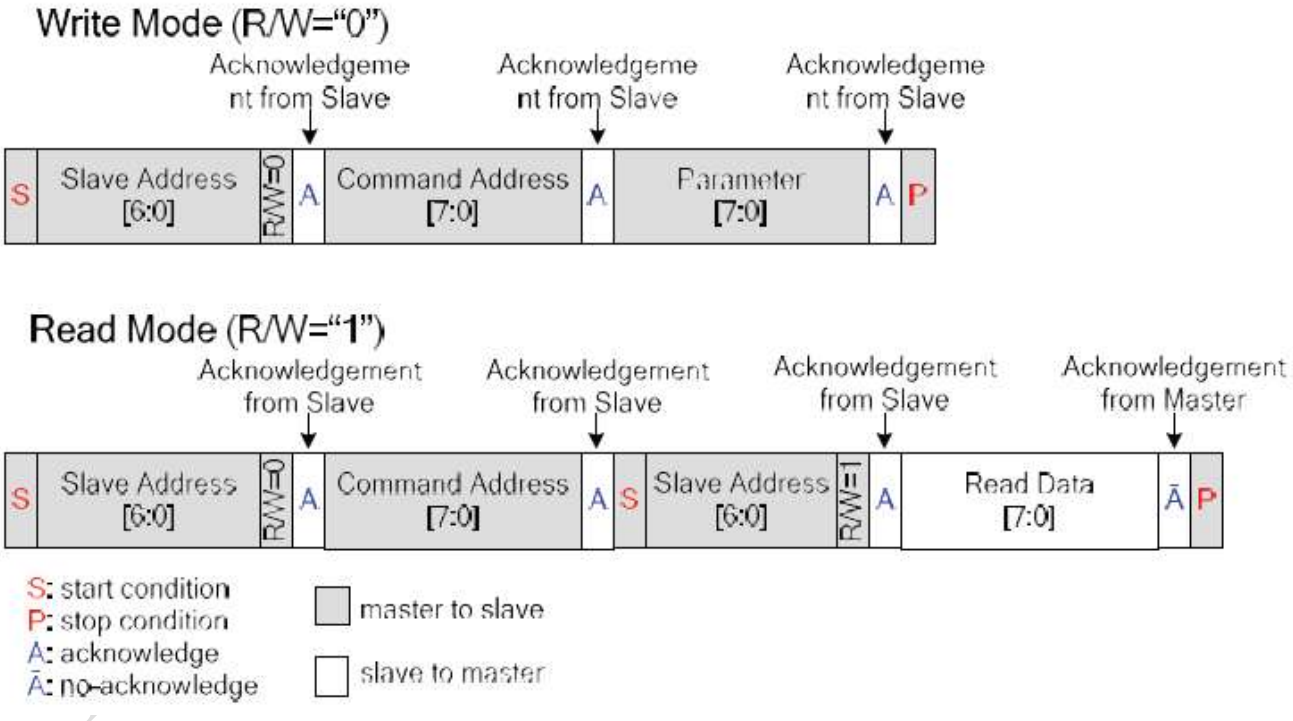


5. I2C Interface Protocol

The driver supports command/data write to addressed slaves on the bus. Before any data is transmitted on the I2C Interface, the device which should respond is addressed first. The default slave address is 0111100b and the three times I2C address could be OTP programing.

The sequence is initiated with a START condition (S) from the I2C Interface master, which is followed by the slave address. All slaves with the corresponding address acknowledge in parallel, all the others will ignore the I2C Interface transfer. After acknowledgement, one or more command or data words are followed and define the status of the addressed slaves.

Only the addressed slave makes the acknowledgement after each byte. At the end of the transmission the bus master issues a STOP condition (P). If no acknowledge is generated by the master after a byte, the driver stops transferring data to the master. The register write/ read transference sequence are described as follows.



10.3. RGB Interface

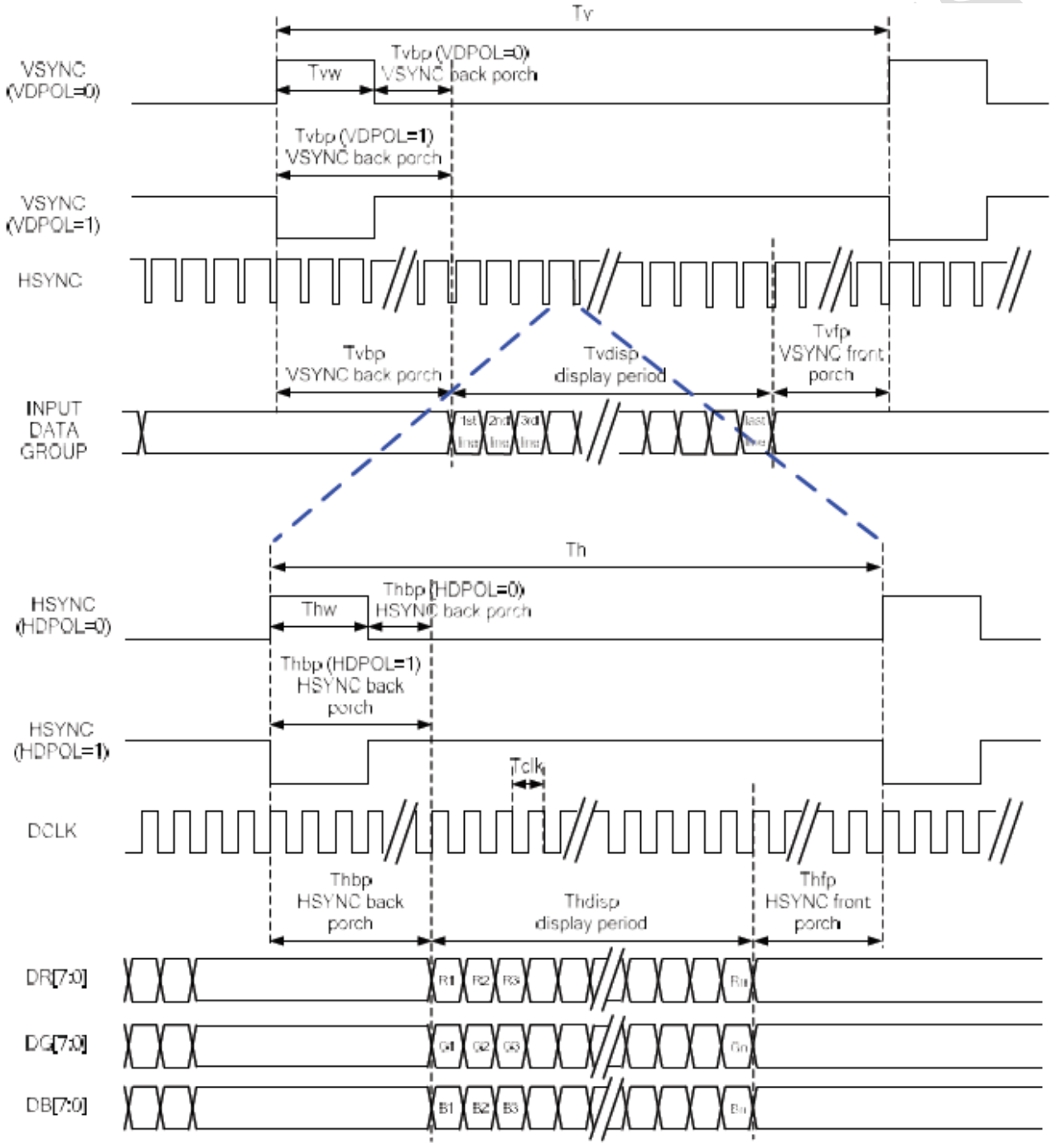
1.Pin Assignment for RGB Interface

Pin		Parallel RGB			Serial RGB		
		888	666	565	888	666	565
VSYNC	SYNC Mode	VSYNC	VSYNC	VSYNC	VSYNC	VSYNC	VSYNC
	DE Mode	x	x	x	x	x	x
HSYNC	SYNC Mode	HSYNC	HSYNC	HSYNC	HSYNC	HSYNC	HSYNC
	DE Mode	x	x	x	x	x	x
DE	SYNC Mode	x	x	x	x	x	x
	DE Mode	DE	DE	DE	DE	DE	DE
CLK		CLK	CLK	CLK	CLK	CLK	CLK
DR0		R0	x	x	x	x	x
DR1		R1	x	x	x	x	x
DR2		R2	R0	x	x	x	x
DR3		R3	R1	R0	x	x	x
DR4		R4	R2	R1	x	x	x
DR5		R5	R3	R2	x	x	x
DR6		R6	R4	R3	x	x	x
DR7		R7	R5	R4	x	x	x
DG0		G0	x	x	D0	x	x
DG1		G1	x	x	D1	x	x
DG2		G2	G0	G0	D2	D0	D0
DG3		G3	G1	G1	D3	D1	D1
DG4		G4	G2	G2	D4	D2	D2
DG5		G5	G3	G3	D5	D3	D3
DG6		G6	G4	G4	D6	D4	D4
DG7		G7	G5	G5	D7	D5	D5
DB0		B0	x	x	x	x	x
DB1		B1	x	x	x	x	x
DB2		B2	B0	x	x	x	x
DB3		B3	B1	B0	x	x	x
DB4		B4	B2	B1	x	x	x
DB5		B5	B3	B2	x	x	x
DB6		B6	B4	B3	x	x	x
DB7		B7	B5	B4	x	x	x

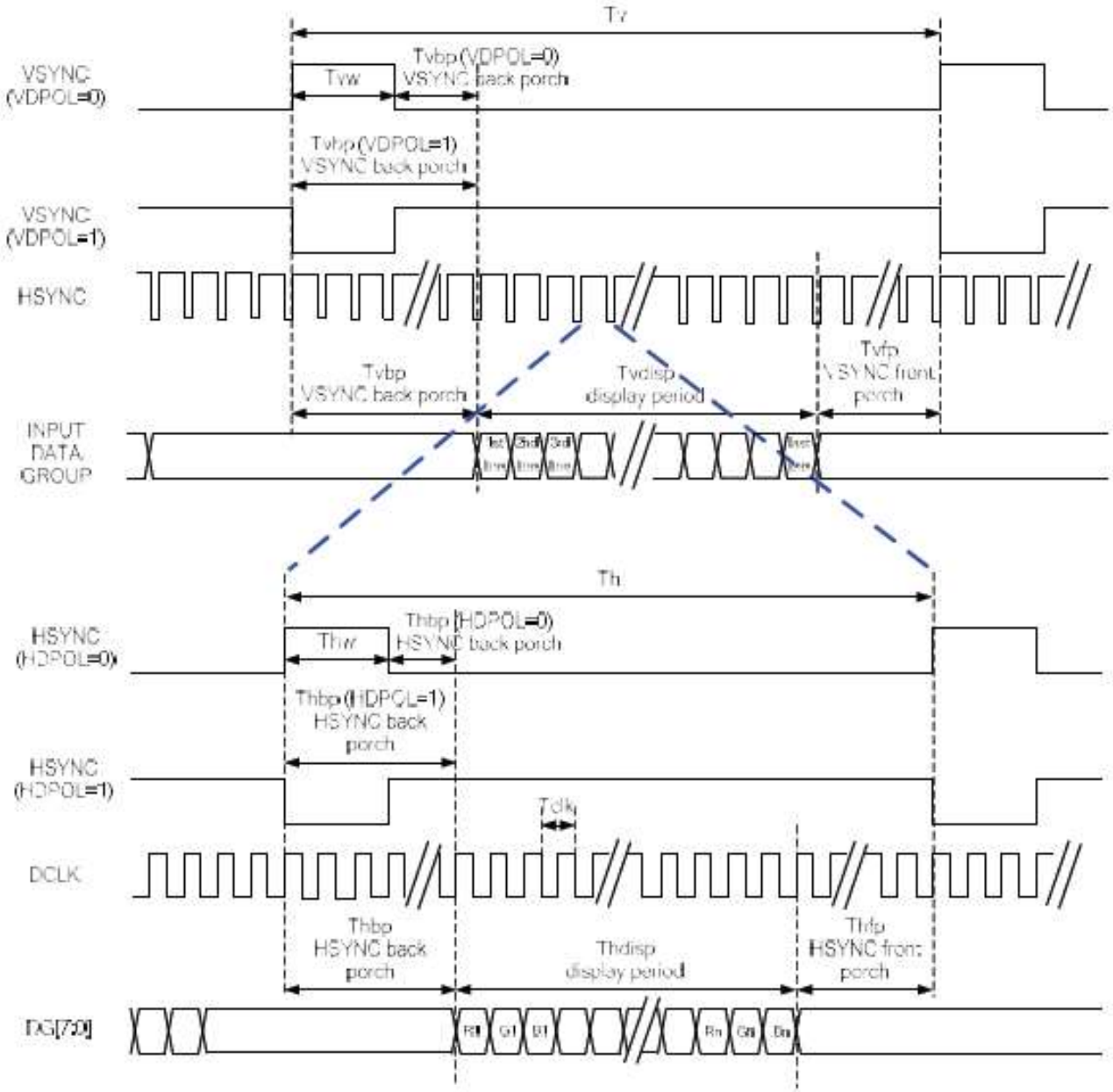
RGB Mode Selection Table	DCLK	HSYNC	VSYNC	DE
SYNC - DE Mode	Input	Input	Input	Input
SYNC Mode	Input	Input	Input	GND
DE Mode	Input	GND	GND	Input

Note: “Input” means these signals are driven by host side

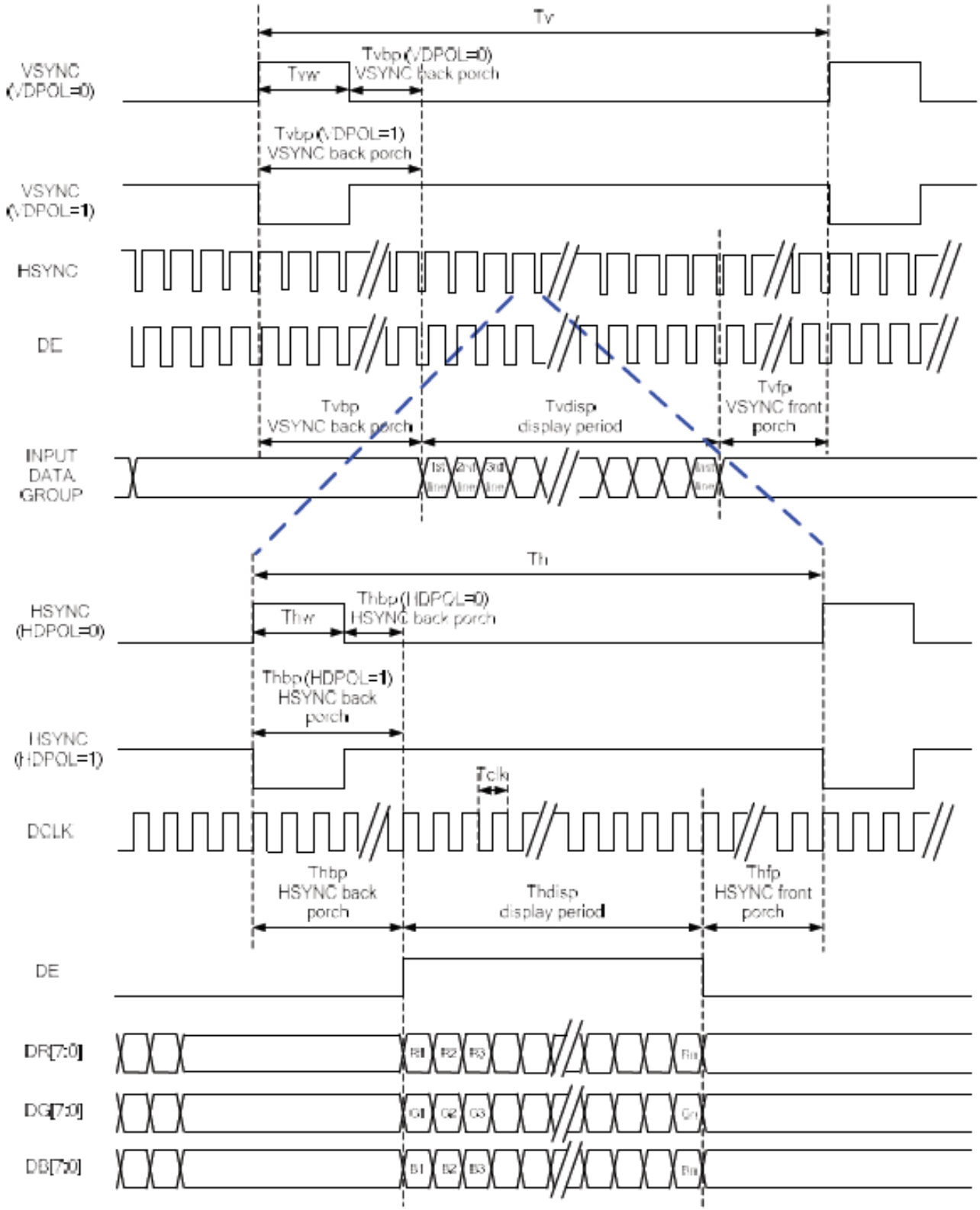
2. Parallel RGB SYNC Mode



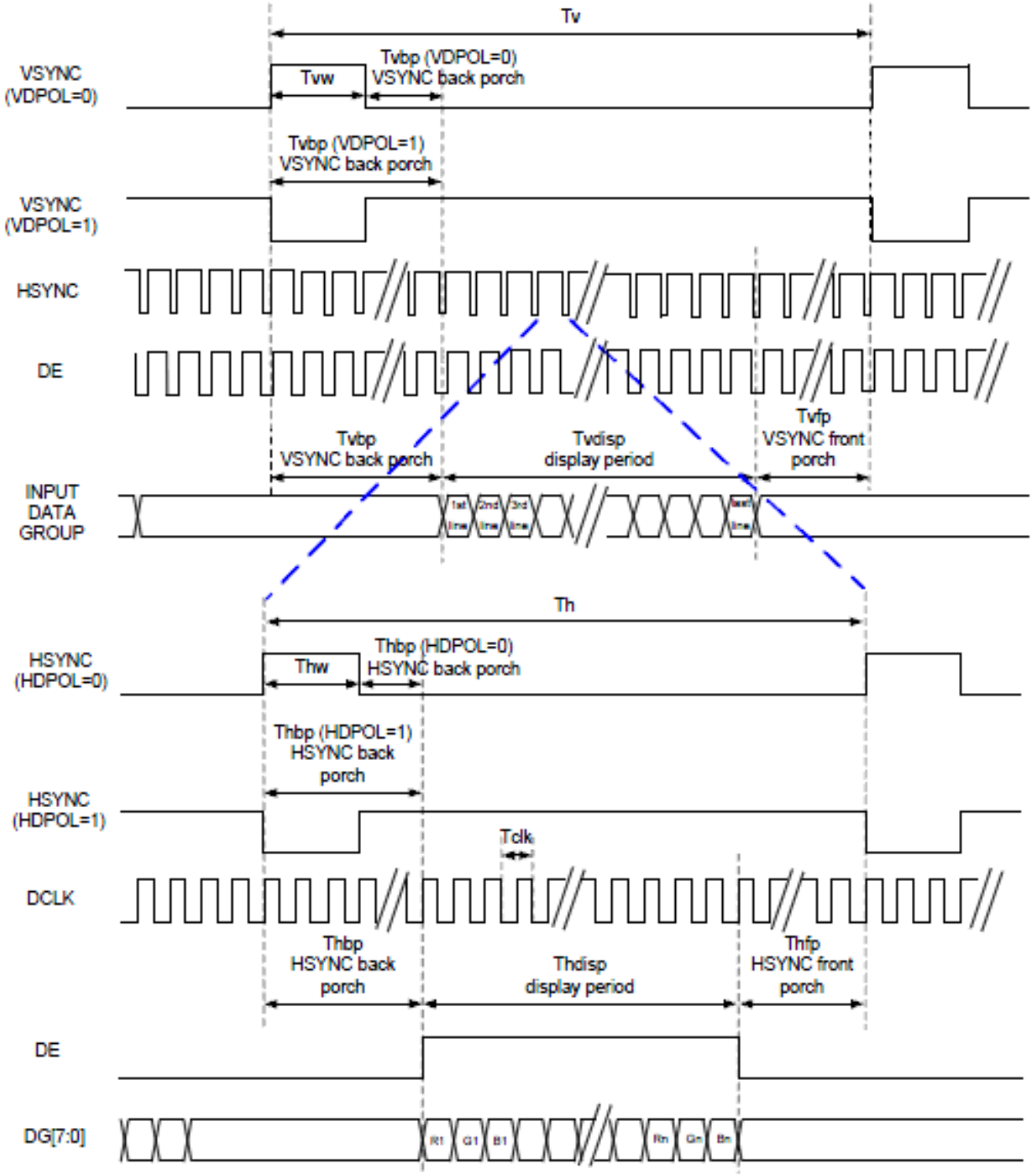
3. Serial RGB SYNC Mode



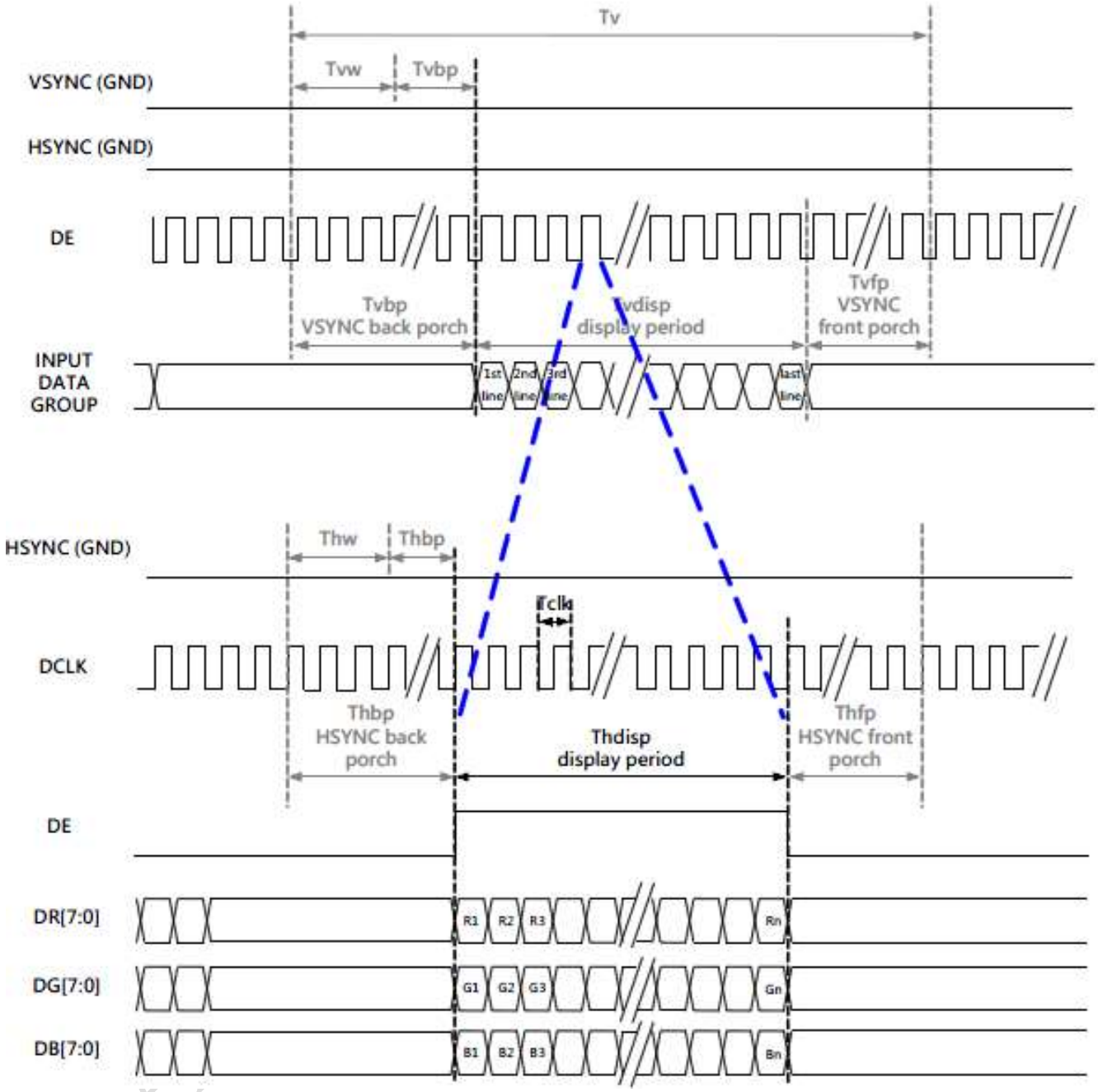
4. Parallel RGB SYNC-DE Mode



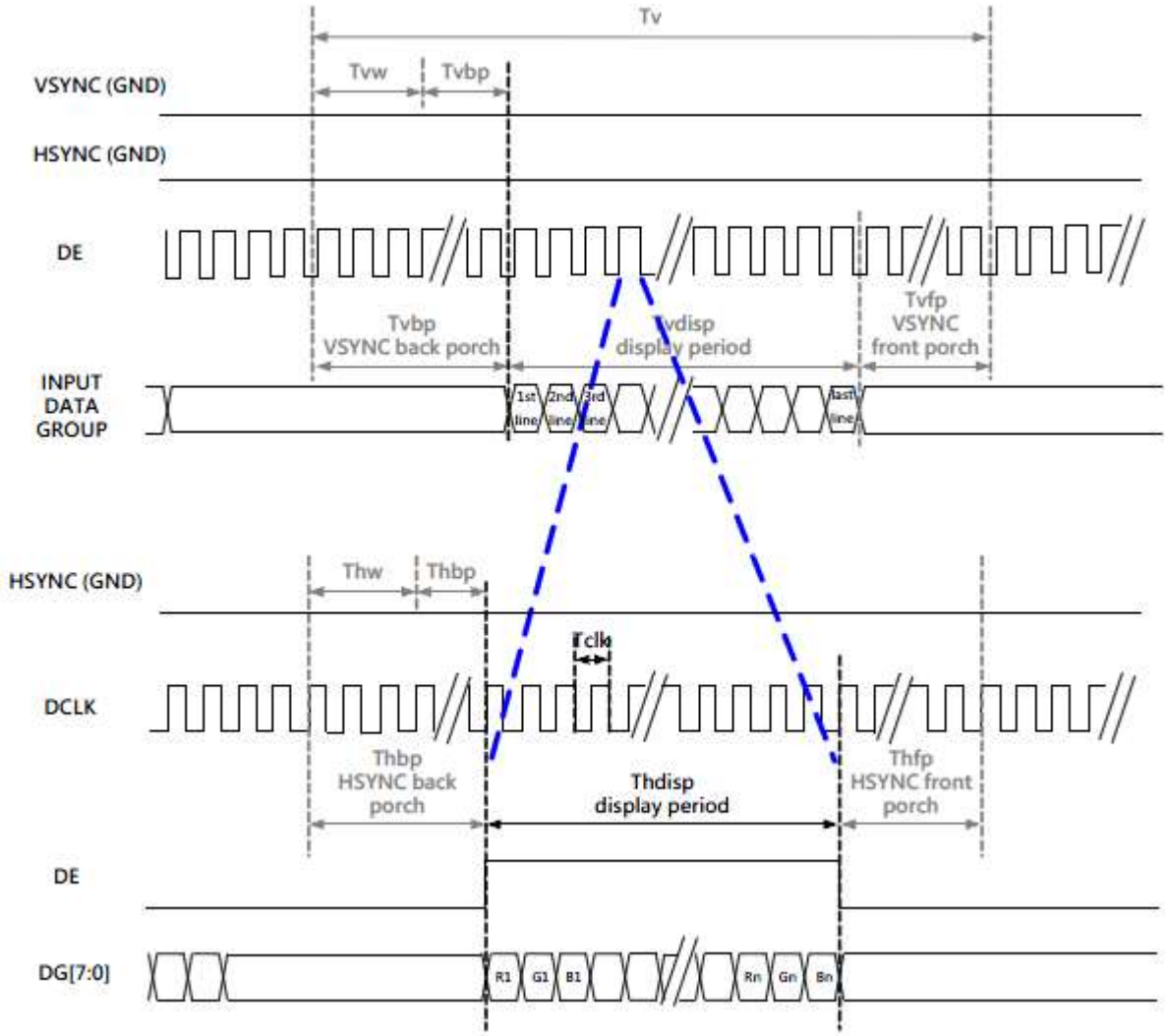
5. Serial RGB SYNC-DE Mode



6. Parallel RGB DE Mode



7. Serial RGB DE Mode



8. Parallel RGB Input Timing Table

Parallel 24-bit RGB Input Timing (PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25 C)

Parallel 24-bit RGB Input Timing Table							
Item		Symbol	Min.	Typ.	Max.	Unit	Note
DCLK Frequency		Fclk	5	6	8	MHz	
DCLK Period		Tclk	125	167	200	ns	
HSYNC	Period Time	Th	325	371	438	DCLK	
	Display Period	Thdisp		320		DCLK	
	Back Porch	Thbp	3	43	43	DCLK	SYNC mode back porch control by H_BLANKING[7:0] setting Thbp= H_BLANKING[7:0]
	Front Porch	Thfp	2	8	75	DCLK	
	Pulse Width	Thw	2	4	43	DCLK	
VSYNC	Period Time	Tv	244	260	289	HSYNC	
	Display Period	Tvdisp		240		HSYNC	
	Back Porch	Tvbp	2	12	12	HSYNC	SYNC mode back porch control by V_BLANKING[7:0] setting Tvbp= V_BLANKING[7:0]
	Front Porch	Tvfp	2	8	37	HSYNC	
	Pulse Width	Tvw	2	4	12	HSYNC	

Note: It is necessary to keep Tvbp =12 and Thbp =43 in sync mode. DE mode is unnecessary to keep it.

9. Serial RGB Input Timing Table

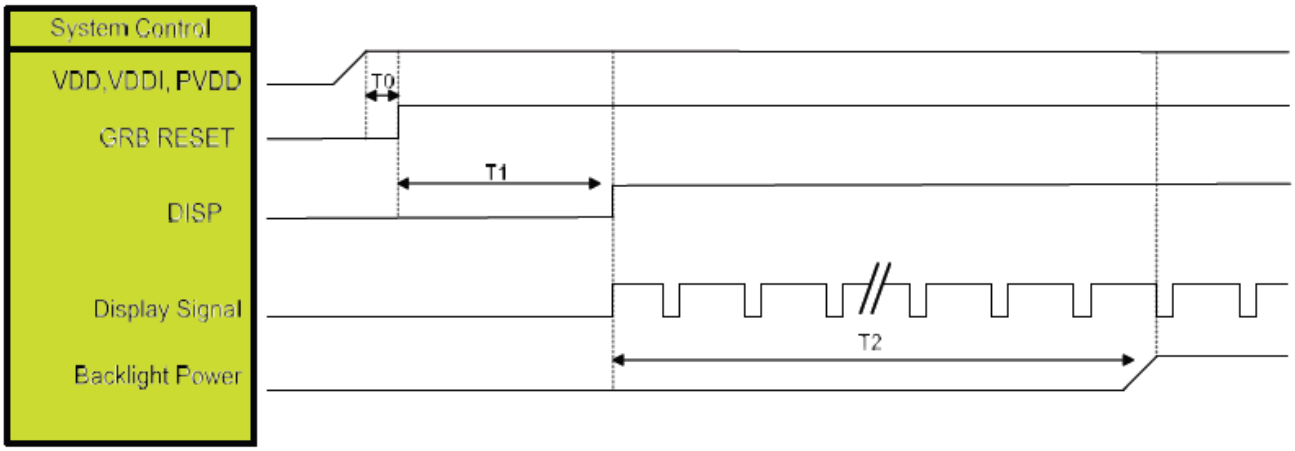
Serial 8-bit RGB Input Timing (PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25 C)

Serial 8-bit RGB Input Timing Table							
Item		Symbol	Min.	Typ.	Max.	Unit	Remark
DCLK Frequency		Fclk	15	18	21	MHz	
DCLK Period		Tclk	47	55	66	ns	
HSYNC	Period Time	Th	965	1011	1078	DCLK	
	Display Period	Thdisp		960		DCLK	
	Back Porch	Thbp	3	43	43	DCLK	SYNC mode back porch control by H_BLANKING[7:0] setting Thbp= H_BLANKING[7:0]
	Front Porch	Thfp	2	8	75	DCLK	
	Pulse Width	Thw	2	4	43	DCLK	
VSYNC	Period Time	Tv	244	260	289	HSYNC	
	Display Period	Tvdisp		240		HSYNC	
	Back Porch	Tvbp	2	12	12	HSYNC	SYNC mode back porch control by V_BLANKING[7:0] setting Tvbp= V_BLANKING[7:0]
	Front Porch	Tvfp	2	8	37	HSYNC	
	Pulse Width	Tvw	2	4	12	HSYNC	

Note: It is necessary to keep Tvbp =12 and Thbp =43 in sync mode. DE mode is unnecessary to keep it.

10.4. POWER ON/OFF SEQUENCE

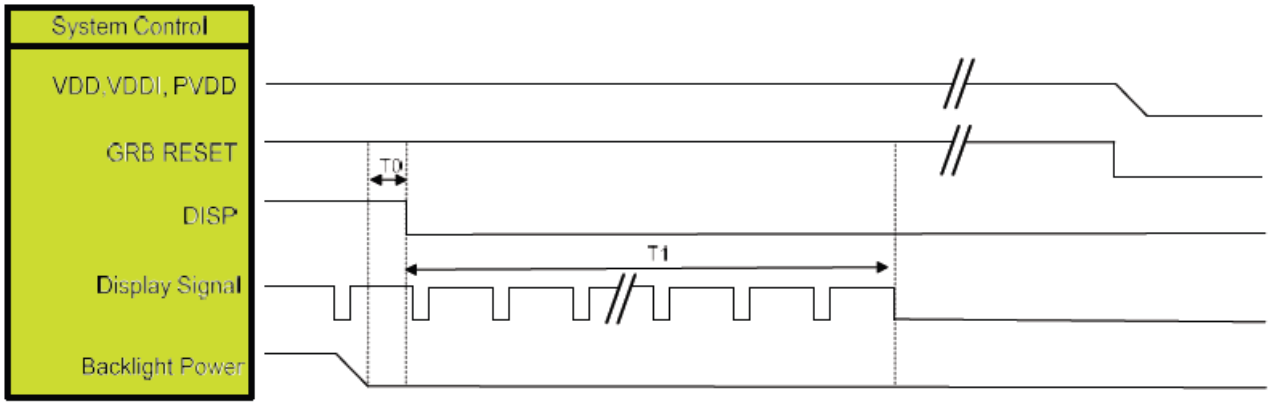
1. Power On Sequence



Symbol	Description	Min. Time	Unit
T0	System power stability to GRB RESET signal	0	ms
T1	GRB RESET= "High" to DISP="High"	10	ms
T2	Display Signal output to Backlight Power on	250	ms

Note: Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0]

2. Power Off Sequence



Symbol	Description	Min. Time	Unit
T0	Backlight Power off to DISP="Low"	5	ms
T1	DISP="Low" to IC internal voltage discharge complete	80	ms

Note: Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0]

11.Optical Characteristics

Item		Symbol	Condition.	Min	Typ.	Max.	Unit	Remark
Response time		Tr+ Tf	θ=0°、Φ=0°	-	30	40	ms	Note 3
Contrast ratio		CR	At optimized viewing angle	640	800	-	-	Note 4
Color Chromaticity	White	Wx	θ=0°、Φ=0	0.26	0.31	0.36	-	Note 2,6,7
		Wy		0.30	0.35	0.40	-	
Viewing angle	Hor.	ΘR	CR≧10	70	80	-	Deg.	Note 1
		ΘL		70	80	-		
	Ver.	ΦT		70	80	-		
		ΦB		70	80	-		
Brightness		-	-	300	400	-	cd/m^2	Center of display
Uniformity		(U)	-	75	-	-	%	Note 5

Ta=25±2℃, IL=20mA

Note 1: Definition of viewing angle range

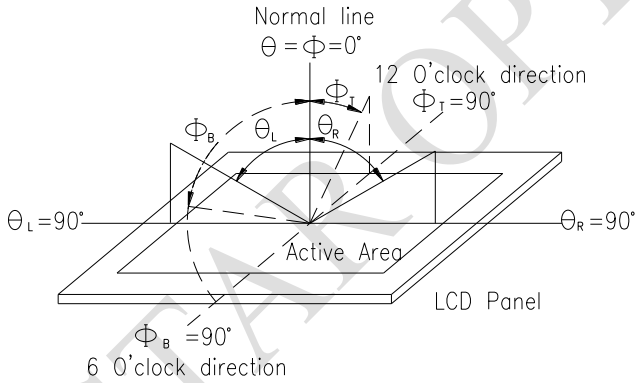


Fig. 11.1. Definition of viewing angle

Note 2: Test equipment setup:

After stabilizing and leaving the panel alone at a driven temperature for 10 minutes, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room. Optical specifications are measured by Topcon BM-7orBM-5 luminance meter 1.0° field of view at a distance of 50cm and normal direction.

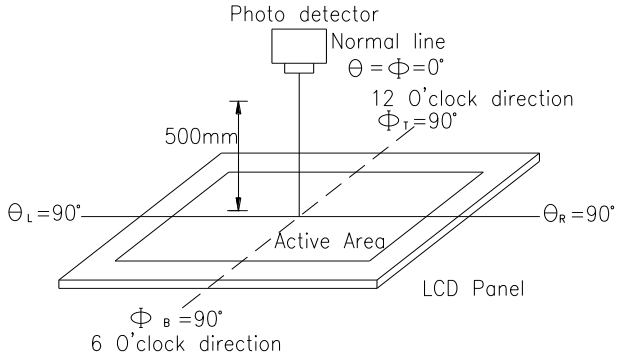
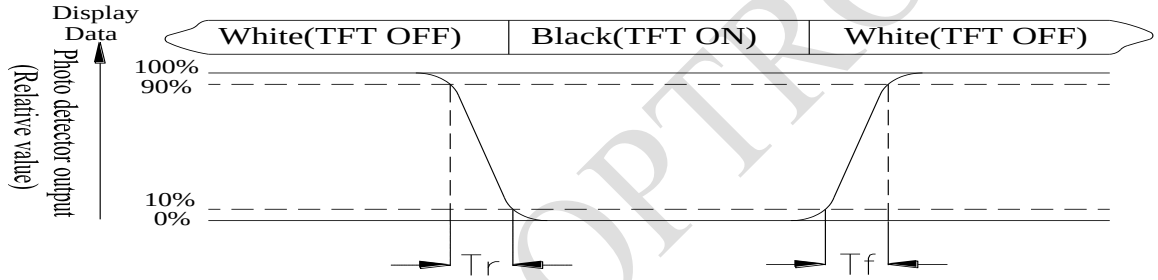


Fig. 11.2. Optical measurement system setup

Note 3: Definition of Response time:
The response time is defined as the LCD optical switching time interval between “White” state and “Black” state. Rise time, Tr, is the time between photo detector output intensity changed from 90%to 10%. And fall time, Tf, is the time between photo detector output intensity changed from 10%to 90%



Note 4: Definition of contrast ratio:
The contrast ratio is defined as the following expression.

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$$

Note 5: Definition of Luminance Uniformity
Active area is divided into 9 measuring areas (reference the picture in below). Every measuring point is placed at the center of each measuring area.
Luminance Uniformity (U) = Lmin/Lmax x100%
L = Active area length
W = Active area width

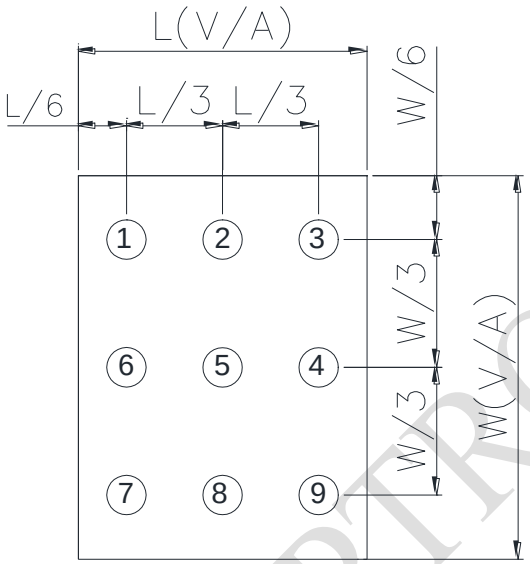


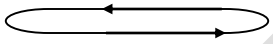
Fig11.3. Definition of uniformity

Note 6: Definition of color chromaticity (CIE 1931)
Color coordinates measured at the center point of LCD

Note 7: Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

12.Reliability

Content of Reliability Test (Super Wide temperature, -30□~85□)

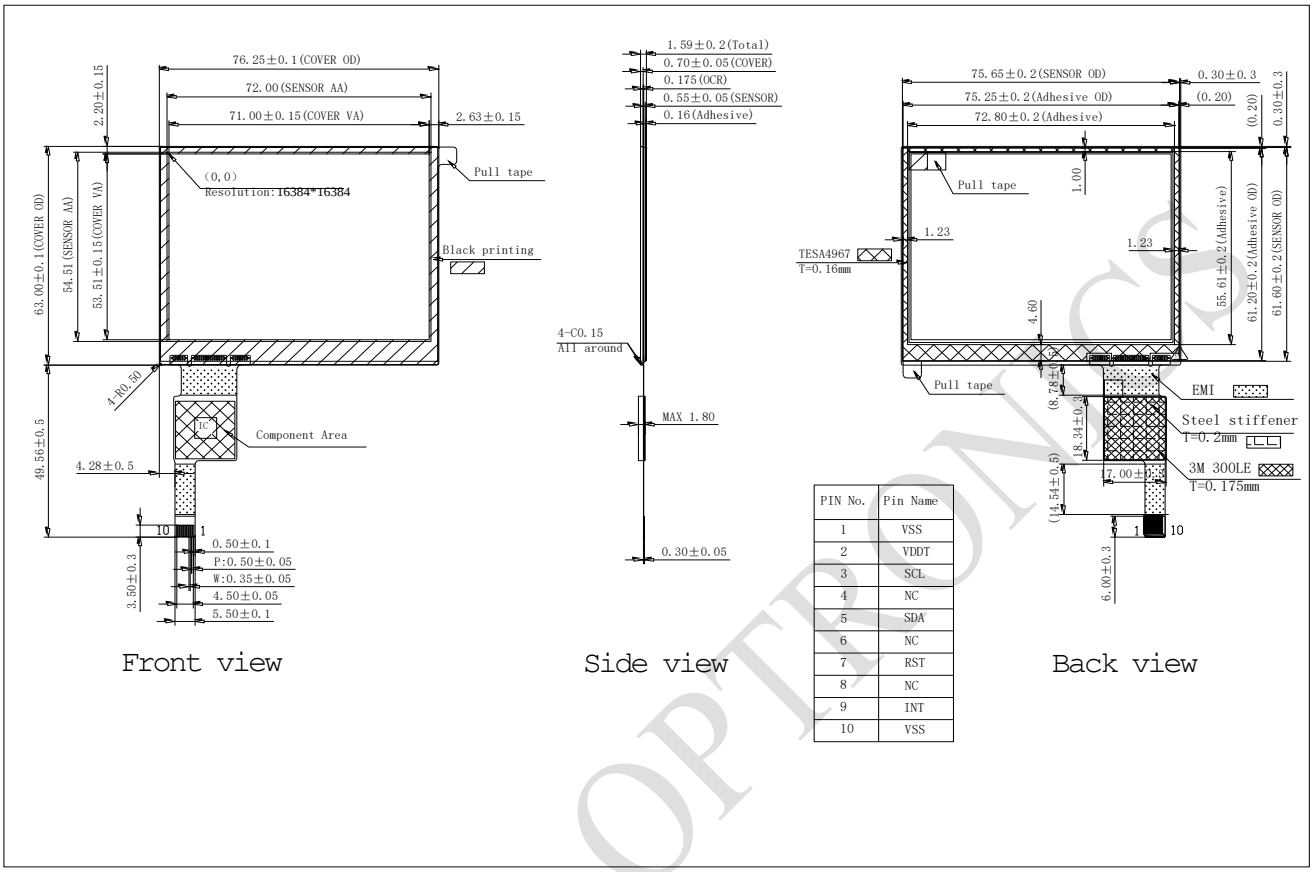
Environmental Test			
Test Item	**Content of Test**	**Test Condition**	**Note**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85□ 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30□ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	85□ 200hrs	——
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-30□ 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60□,90%RH max	60□,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -30□ 25□ 85□  30min 5min 30min 1 cycle	-30□/85□ 10 cycles	——
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	**3**
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact) ,±800v(air), RS=330Ω CS=150pF 10 times	——

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

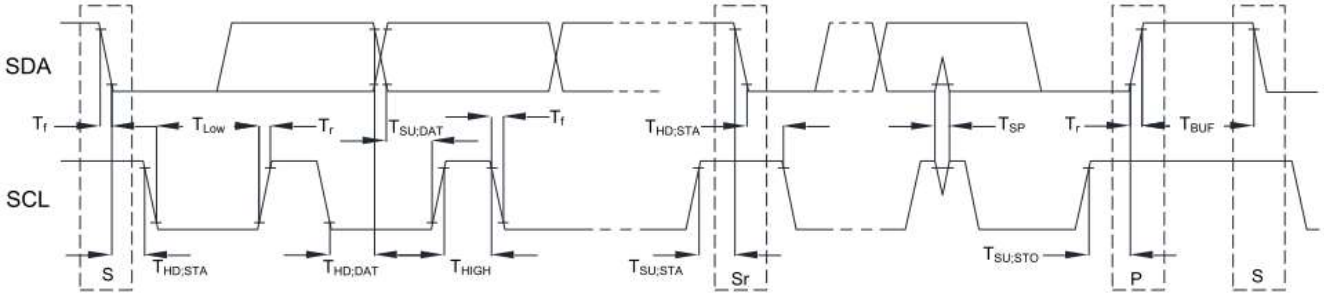
Note3: The packing have to including into the vibration testing.

13.Touch Panel Information



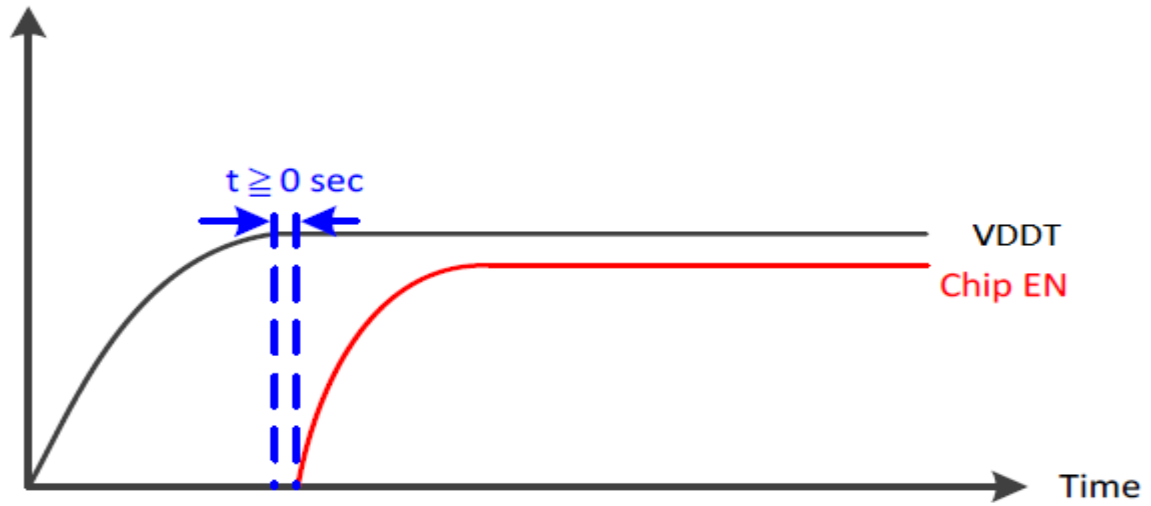
PIN No.	Pin Name
1	VSS
2	VDDT
3	SCL
4	NC
5	SDA
6	NC
7	RST
8	NC
9	INT
10	VSS

13.1. I2C AC Characteristics

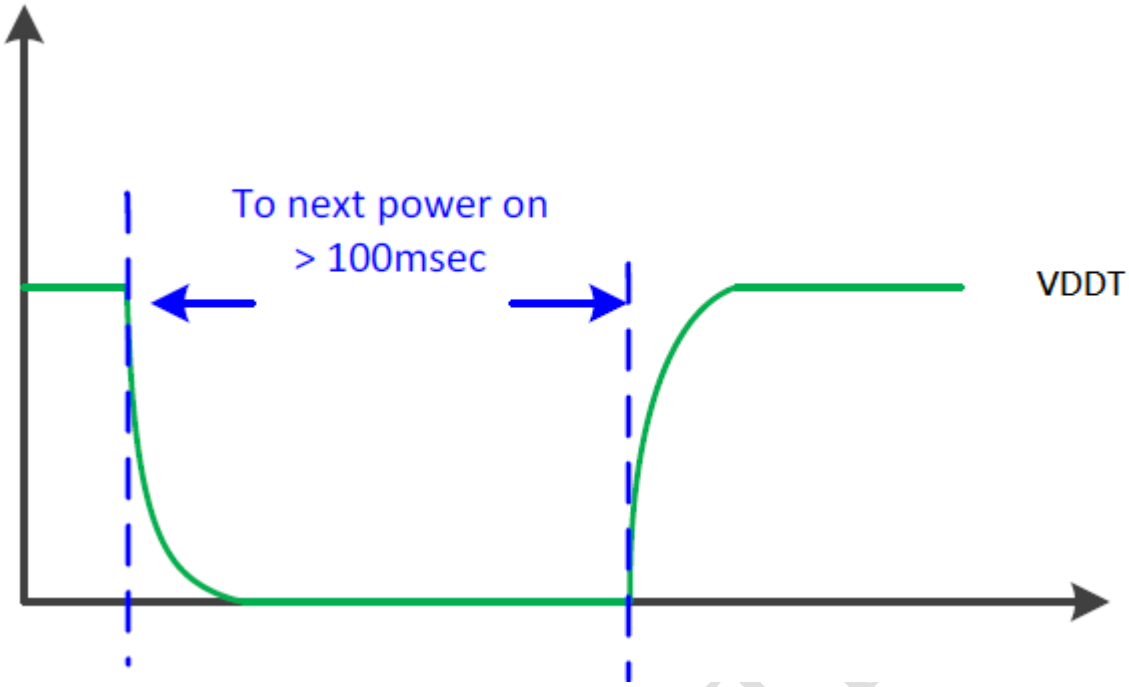


Item	Symbol	100kHz		400kHz		Unit
		Min.	Max.	Min.	Max.	
SCL standard mode clock frequency	FSCL	0	100	0	400	kHz
Hold time (repeated) START condition. After this period, the first clock is generated.	THD;STA	4	--	0.6	--	us
LOW period of the SCL clock	TLOW	4.7	--	1.3	--	us
HIGH period of the SCL clock	THIGH	4	--	0.6	--	us
Setup time for a repeat START condition.	TSU;STA	4.7	--	0.6	--	us
Data hold time	THD;DAT	0	3.45	0	0.9	us
Data setup time	TSU;DAT	250	--	100	--	ns
Rising time of both SDA and SCL signals	Tr	--	1000	--	300	ns
Falling time of both SDA and SCL signals	Tf	--	300	--	300	ns
Setup time for STOP condition.	TSU;STO	4	--	0.6	--	us
Free time between STOP and START condition	TBUF	4.7	--	1.3	--	us
Pulse width of spikes which must be suppressed by input filter	TSP	--	--	0	50	ns

13.2. Power On Sequence



13.3. Power Off to Power On Sequence



LCM Sample Estimate Feedback Sheet		
Module Number：_____		
1、Panel Specification：		
1. Panel Type：	□ Pass	□ NG ,_____
2. View Direction：	□ Pass	□ NG ,_____
3. Numbers of Dots：	□ Pass	□ NG ,_____
4. View Area：	□ Pass	□ NG ,_____
5. Active Area：	□ Pass	□ NG ,_____
6.Operating Temperature：	□ Pass	□ NG ,_____
7.Storage Temperature：	□ Pass	□ NG ,_____
8.Others：_____		
2、Mechanical Specification：		
1. PCB Size：	□ Pass	□ NG ,_____
2.Frame Size：	□ Pass	□ NG ,_____
3.Materal of Frame：	□ Pass	□ NG ,_____
4.Connector Position：	□ Pass	□ NG ,_____
5.Fix Hole Position：	□ Pass	□ NG ,_____
6.Backlight Position：	□ Pass	□ NG ,_____
7. Thickness of PCB：	□ Pass	□ NG ,_____
8. Height of Frame to PCB：	□ Pass	□ NG ,_____
9.Height of Module：	□ Pass	□ NG ,_____
10.Others：	□ Pass	□ NG ,_____
3、Relative Hole Size：		
1.Pitch of Connector：	□ Pass	□ NG ,_____
2.Hole size of Connector：	□ Pass	□ NG ,_____
3.Mounting Hole size：	□ Pass	□ NG ,_____
4.Mounting Hole Type：	□ Pass	□ NG ,_____
5.Others：	□ Pass	□ NG ,_____
4、Backlight Specification：		
1.B/L Type：	□ Pass	□ NG ,_____
2.B/L Color：	□ Pass	□ NG ,_____
3.B/L Driving Voltage (Reference for LED Type)：□ Pass □ NG ,_____		
4.B/L Driving Current：	□ Pass	□ NG ,_____
5.Brightness of B/L：	□ Pass	□ NG ,_____
6.B/L Solder Method：	□ Pass	□ NG ,_____
7.Others：	□ Pass	□ NG ,_____

>> **Go to page 2** <<

Module Number：_____		
5、Electronic Characteristics of Module：		
1.Input Voltage：	□ Pass	□ NG ,_____
2.Supply Current：	□ Pass	□ NG ,_____
3.Driving Voltage for LCD：	□ Pass	□ NG ,_____
4.Contrast for LCD：	□ Pass	□ NG ,_____
5.B/L Driving Method：	□ Pass	□ NG ,_____
6.Negative Voltage Output：	□ Pass	□ NG ,_____
7.Interface Function：	□ Pass	□ NG ,_____
8.LCD Uniformity：	□ Pass	□ NG ,_____
9.ESD test：	□ Pass	□ NG ,_____
10.Others：	□ Pass	□ NG ,_____

6、Summary：

Sales signature：_____

Customer Signature：_____ **Date**：__/__/__